

POLISHING PADS AND PLANARIZING MACHINES FOR
MECHANICAL OR CHEMICAL-MECHANICAL PLANARIZATION OF
MICROELECTRONIC-DEVICE SUBSTRATE ASSEMBLIES, AND METHODS
FOR MAKING AND USING SUCH PADS AND MACHINES

ABSTRACT OF THE DISCLOSURE

Methods for manufacturing polishing pads for planarizing microelectronic devices are disclosed. In one aspect, a method includes forming contour surfaces over a surface of a backing member and covering the contour surfaces with a cover layer of hard material that conforms to the contour surfaces to form nodules projecting away from the surface of the backing member. In another aspect, a method includes distributing pattern elements over a surface of a backing member to define contour surfaces projecting away from the surface of the backing member, and forming a layer of a hard material at least on the pattern elements to conform to the contour surfaces, the portions of the cover layer over the contour surfaces projecting away from the surface of the backing member to define abrasive nodules.